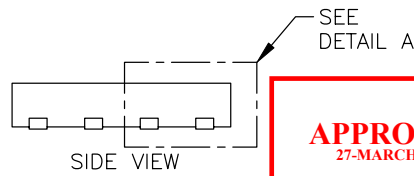
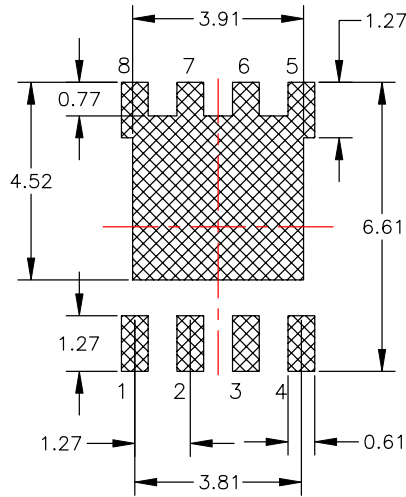
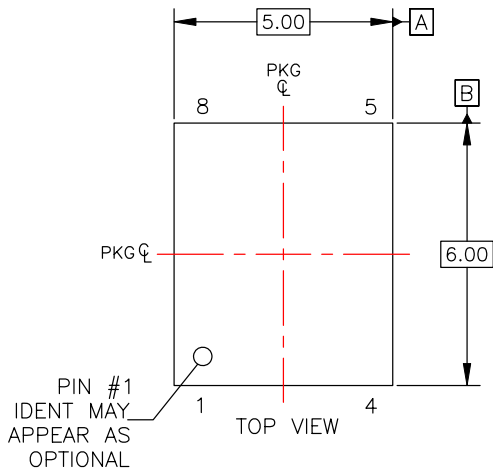
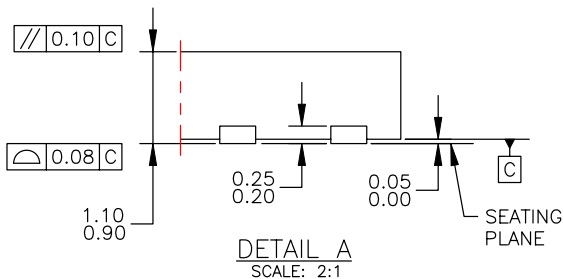
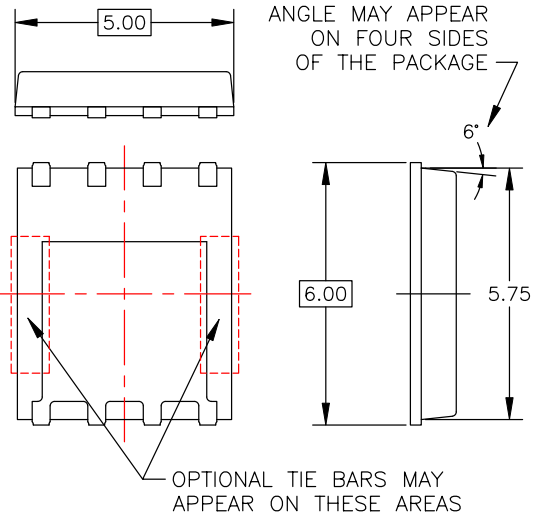
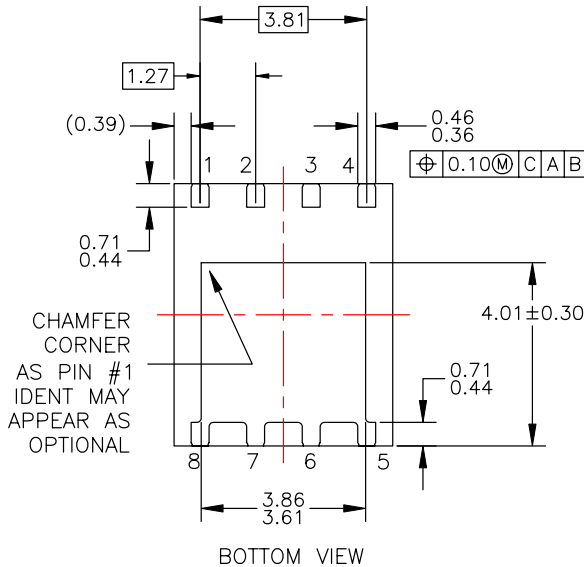


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| REVISIONS | | | |
|-----------|--|-----------|-----------|
| LTR | DESCRIPTION | DATE | NAME/SITE |
| 1 | RELEASE TO DOCUMENT CONTROL | 1AUG2006 | CBE/CB |
| 2 | CHG LD THICKNESS FR 0.20±0.025 TO 0.25 CHG TOTAL PKG THICKNESS FR 1.00 TO 1.05 ADD TIE BAR ON PAD AND PKG SIDE DRAFT ANGLE AS OPTIONAL; CHG EXPOSED PAD WIDTH FR 3.66-3.86 TO 3.61-3.86; CHG EXPOSED LD LENGTH FR 0.44-0.64 TO 0.44-0.71; TRANSFER DATUM PLANE 'C' TO DETAIL A; ADD MOLD FLASH OR BURRS 0.1MM LIMIT ON NOTE C. | 20NOV2007 | CBE/CB |



APPROVED
27-MARCH-2008



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. AA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08AREV2

| APPROVALS | | DATE | FAIRCHILD SEMICONDUCTOR™ | | |
|--------------------------------|--|---------------|--|-------------------------------|----------|
| DRAWN: J.U. COMPARATIVO JR. | | 30JAN2008 | | | |
| CHECKED: C.B. ESTACIO | | | | | |
| APPROVED: M. GESTOLE | | | | | |
| G.S. BAJE | | | 8LD, PQFN, JEDEC MO-240 AA, 5.0X6.0MM | | |
| PROJECTION | | SCALE 1:1 | SIZE N.A. | DRAWING NUMBER MKT-PQFN08A | REV 2 |
| | | FORMERLY: N/A | SHEET : 1 OF 1 | | |